

Title (en)

PROCESS FOR REALISING A RESIST COATING IN A RECESS ON THE SURFACE OF A SUBSTRATE, IN PARTICULAR A WAFER

Title (de)

VERFAHREN ZUR RESIST-BESCHICHTUNG EINER VERTIEFUNG IN DER OBERFLÄCHE EINES SUBSTRATS, INSBESONDERE EINES WAFERS

Title (fr)

PROCÉDÉ POUR DÉPOSER UN RÉSITE DANS DES CREUX À LA SURFACE D'UN SUBSTRAT, EN PARTICULIER D'UN WAFER

Publication

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Application

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Abstract (en)

[origin: WO2010023156A1] The invention provides a method for resist coating a recess in the surface of a substrate, in particular a wafer. This involves filling the recess with a resist solution and heating the substrate, so that the solvent of the resist solution evaporates and the bottom of the recess and at least portions of the inner walls of the recess that adjoin the bottom are coated with the resist.

IPC 8 full level

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